

ALLPCB

SOLDERABILITY TEST REPORT

Order P/N	Customer P/N	Customer	
JP-2Y2079995	J2Y-2436190	H19981A	
Item	◆ HAL	◇ Plating Gold	◇ Immersion Tin

Condition

Temperature	260±5℃	Time	5 second / once
Contents	Results		
1. Wettability	ACC		
2. Hole Void	ACC		
3. Solder Mask Blister	ACC		
4. Copper-cold Blister	ACC		
5. Warp-Twist	ACC		
6. Status of Laminate	ACC		

Note:

Conclusion:

◆ ACC

◇ REJ

◇ UAI

QA Inspected By: 鲁世蓓

QA Approved By: 付家贵

